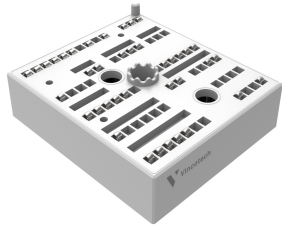
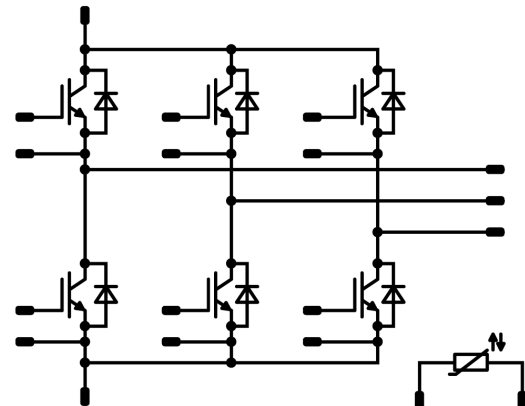




| MiniSKiiP® PACK 2 | 1200 V / 25 A |
|--|--|
| <p>Topology features</p> <ul style="list-style-type: none">• Inverter• Kelvin Emitter for improved switching performance• Temperature sensor | <p>MiniSKiiP® 2 16 mm housing</p>  |
| <p>Component features</p> <ul style="list-style-type: none">• Easy paralleling• Low turn-off losses• Low collector emitter saturation voltage• Positive temperature coefficient• Short tail current• Switching optimized for EMC | <p>Schematic</p>  |
| <p>Housing features</p> <ul style="list-style-type: none">• Base isolation: Al₂O₃• Easy assembly in one mounting step• Flexible PCB design w/o pin holes• Rugged solderless spring contacts | |
| <p>Target applications</p> <ul style="list-style-type: none">• General Purpose Drives• Industrial Drives | |
| <p>Types</p> <ul style="list-style-type: none">• 80-M2126PA025M7-K716F70 | |



Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|-----------------------------------|------------|--|----------|--------------------|
| Inverter Switch | | | | |
| Collector-emitter voltage | V_{CES} | | 1200 | V |
| Collector current (DC current) | I_C | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 38 | A |
| Repetitive peak collector current | I_{CRM} | t_p limited by T_{jmax} | 50 | A |
| Total power dissipation | P_{tot} | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 99 | W |
| Gate-emitter voltage | V_{GES} | | ± 20 | V |
| Short circuit ratings | i_{SC} | $V_{GE} = 15\text{ V}$, $V_{CC} = 800\text{ V}$ $T_j = 150\text{ °C}$ | 9,5 | μs |
| Maximum junction temperature | T_{jmax} | | 175 | $^{\circ}\text{C}$ |

Inverter Diode

| | | | | |
|---------------------------------|------------|---------------------------------------|------|--------------------|
| Peak repetitive reverse voltage | V_{RRM} | | 1200 | V |
| Forward current (DC current) | I_F | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 37 | A |
| Repetitive peak forward current | I_{FRM} | t_p limited by T_{jmax} | 50 | A |
| Total power dissipation | P_{tot} | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 75 | W |
| Maximum junction temperature | T_{jmax} | | 175 | $^{\circ}\text{C}$ |

Module Properties

Thermal Properties

| | | | | |
|---|-----------|--|----------------------------|--------------------|
| Storage temperature | T_{stg} | | -40...+125 | $^{\circ}\text{C}$ |
| Operation temperature under switching condition | T_{jop} | | -40...+($T_{jmax} - 25$) | $^{\circ}\text{C}$ |

Isolation Properties

| | | | | |
|----------------------------|------------|---|------------|----|
| Isolation voltage | V_{isol} | DC Test Voltage* $t_p = 2\text{ s}$ | 5500 | V |
| Creepage distance | | With std lid For more informations see handling instructions | 6,3 | mm |
| Clearance | | With std lid For more informations see handling instructions | 6,3 | mm |
| Comparative Tracking Index | CTI | | ≥ 600 | |

*100 % tested in production



Vincotech

Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|-----------|--------|------------------------------|---|-------------------------------------|------------|-----|--------|-----|--|------|
| | | V_{GE} [V] V_{GS} [V] | V_{CE} [V] V_{DS} [V] V_F [V] | I_C [A] I_D [A] I_F [A] | T_j [°C] | Min | Typ | Max | | |

Inverter Switch

Static

| | | | | | | | | | | |
|--------------------------------------|---------------|------------------|------|------|--------|------------------|-----|----------------------|--------------------|----|
| Gate-emitter threshold voltage | $V_{GE(th)}$ | | | 10 | 0,0025 | 25 | 5,4 | 6 | 6,6 | V |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | | 15 | | 25 | 25 125 150 | | 1,64 1,89 1,95 | 2,1 ⁽¹⁾ | V |
| Collector-emitter cut-off current | I_{CES} | | 0 | 1200 | | 25 | | | 70 | μA |
| Gate-emitter leakage current | I_{GES} | | 20 | 0 | | 25 | | | 200 | nA |
| Internal gate resistance | r_g | | | | | | | None | | Ω |
| Input capacitance | C_{ies} | | | | | | | 4800 | | pF |
| Output capacitance | C_{oes} | | 0 | 10 | | 25 | | 170 | | pF |
| Reverse transfer capacitance | C_{res} | | | | | | | 57 | | pF |
| Gate charge | Q_g | $V_{CC} = 600$ V | 0/15 | | 25 | 25 | | 180 | | nC |

Thermal

| | | | | | | | | | | |
|--|---------------|--|--|--|--|--|--|------|--|-----|
| Thermal resistance junction to sink ⁽²⁾ | $R_{th(j-s)}$ | $\lambda_{paste} = 2,5$ W/mK (HPTP) | | | | | | 0,96 | | K/W |
|--|---------------|--|--|--|--|--|--|------|--|-----|

Dynamic

| | | | | | | | | | | |
|-----------------------------|--------------|--|--|--|--|------------------|--|----------------------------|--|-----|
| Turn-on delay time | $t_{d(on)}$ | | | | | 25 125 150 | | 164,61 161,57 160,52 | | ns |
| Rise time | t_r | | | | | 25 125 150 | | 29,31 32,98 34,05 | | ns |
| Turn-off delay time | $t_{d(off)}$ | | | | | 25 125 150 | | 172,33 199,45 206,04 | | ns |
| Fall time | t_f | | | | | 25 125 150 | | 97,6 129,8 136,33 | | ns |
| Turn-on energy (per pulse) | E_{on} | $Q_{tFWD} = 1,97$ μC $Q_{tFWD} = 3,15$ μC $Q_{tFWD} = 3,47$ μC | | | | 25 125 150 | | 2,28 2,93 3,12 | | mWs |
| Turn-off energy (per pulse) | E_{off} | | | | | 25 125 150 | | 1,73 2,43 2,66 | | mWs |



Vincotech

80-M2126PA025M7-K716F70
datasheet

Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|--|-------------------|--|---|-------------------------------------|------------------|------------------|---------------------|----------------------------|----|------|
| | | V_{GE} [V] V_{GS} [V] | V_{CE} [V] V_{DS} [V] V_F [V] | I_C [A] I_D [A] I_F [A] | T_j [°C] | Min | Typ | Max | | |
| Inverter Diode | | | | | | | | | | |
| Static | | | | | | | | | | |
| Forward voltage | V_F | | | | 25 125 150 | | 1,63 1,7 1,69 | 2,1 ⁽¹⁾ | | V |
| Reverse leakage current | I_R | $V_r = 1200$ V | | | | 25 | | | 35 | μA |
| Thermal | | | | | | | | | | |
| Thermal resistance junction to sink ⁽²⁾ | $R_{th(j-s)}$ | $\lambda_{paste} = 2,5$ W/mK (HPTP) | | | | | | 1,26 | | K/W |
| Dynamic | | | | | | | | | | |
| Peak recovery current | I_{RM} | | | | | 25 125 150 | | 18,56 20,15 20,44 | | A |
| Reverse recovery time | t_{rr} | | | | | 25 125 150 | | 224,89 345,77 379,55 | | ns |
| Recovered charge | Q_r | $di/dt=638$ A/μs $di/dt=520$ A/μs $di/dt=531$ A/μs | ±15 | 600 | 25 | 25 125 150 | | 1,97 3,15 3,47 | | μC |
| Reverse recovered energy | E_{rec} | | | | | 25 125 150 | | 0,574 1,03 1,15 | | mWs |
| Peak rate of fall of recovery current | $(di_r/dt)_{max}$ | | | | | 25 125 150 | | 250,18 145,51 136,98 | | A/μs |



Vincotech

Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|-----------|--------|--------------|--------------|--------------|--------------|-----------|-----------|------------|-----|------|
| | | V_{GS} [V] | V_{GE} [V] | V_{DS} [V] | V_{CE} [V] | I_D [A] | I_C [A] | T_j [°C] | Min | |

Thermistor

Static

| | | | | | | | | | | |
|--------------------------------|-----------|-------------------------|--|--|--|-----|----|------------------------|---|------------------|
| Rated resistance | R | | | | | 25 | | 1 | | kΩ |
| Deviation of R100 | $A_{R/R}$ | $R_{100} = 1670 \Omega$ | | | | 100 | -2 | | 2 | % |
| Maximum Current | I_{max} | | | | | | | 3 | | mA |
| Power dissipation constant | d | | | | | 25 | | 0,76 | | mW/K |
| A-value | A | | | | | | | $7,635 \times 10^{-3}$ | | 1/K |
| B-value | B | | | | | | | $1,73 \times 10^{-5}$ | | 1/K ² |
| Vincotech Thermistor Reference | | | | | | | | | E | |

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

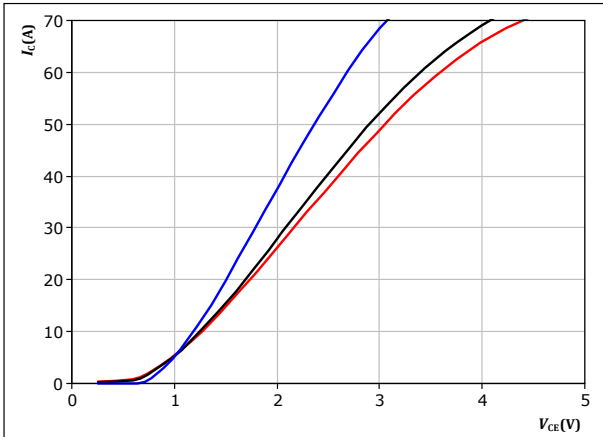


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

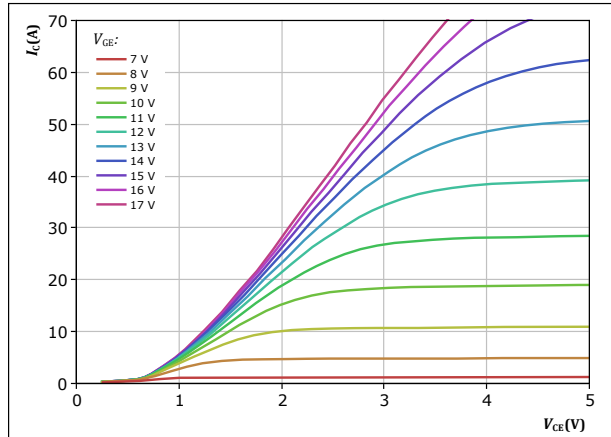


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j:$ — 25 °C
 — 125 °C
 — 150 °C

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

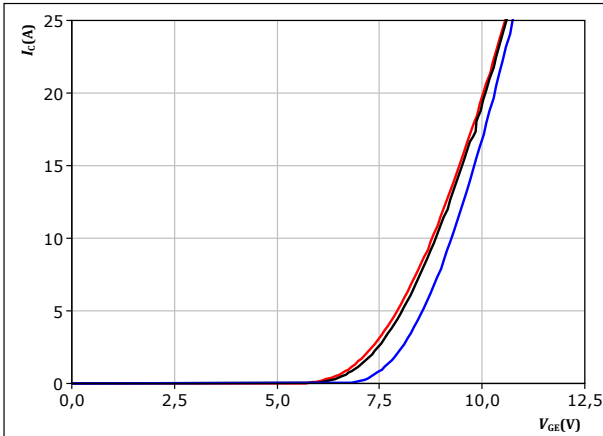


$t_p = 250 \mu s$
 $T_j = 150 \text{ °C}$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

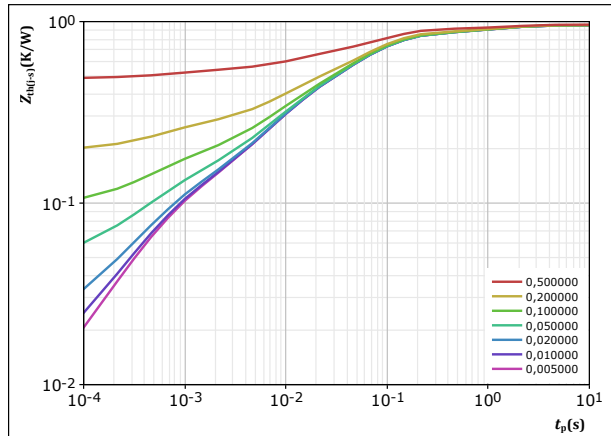


$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_j:$ — 25 °C
 — 125 °C
 — 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,962 \text{ K/W}$
 IGBT thermal model values

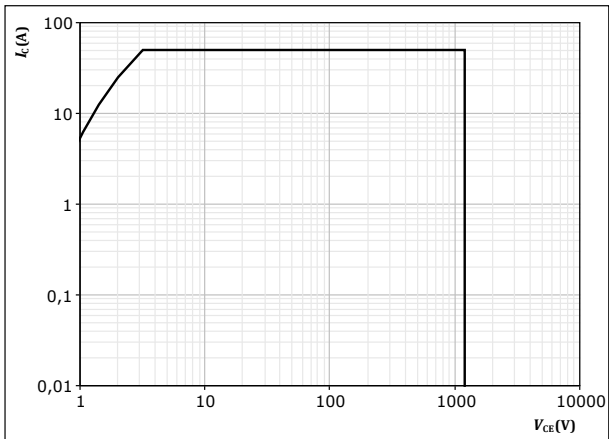
| R (K/W) | τ (s) |
|----------|------------|
| 1,77E-02 | 7,55E+01 |
| 1,19E-01 | 1,09E+00 |
| 5,27E-01 | 6,54E-02 |
| 2,24E-01 | 8,92E-03 |
| 8,28E-02 | 5,37E-04 |



Inverter Switch Characteristics

figure 5. IGBT

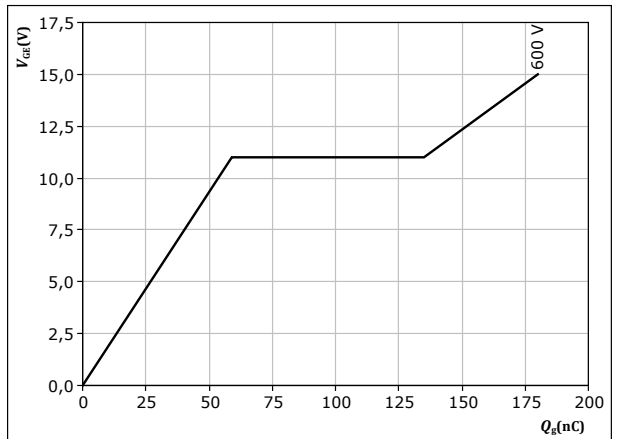
Safe operating area
 $I_C = f(V_{CE})$



$D =$ single pulse
 $T_s = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 6. IGBT

Gate voltage vs gate charge
 $V_{GE} = f(Q_g)$



$I_C = 25$ A
 $T_j = 25$ °C



Inverter Diode Characteristics

figure 7. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

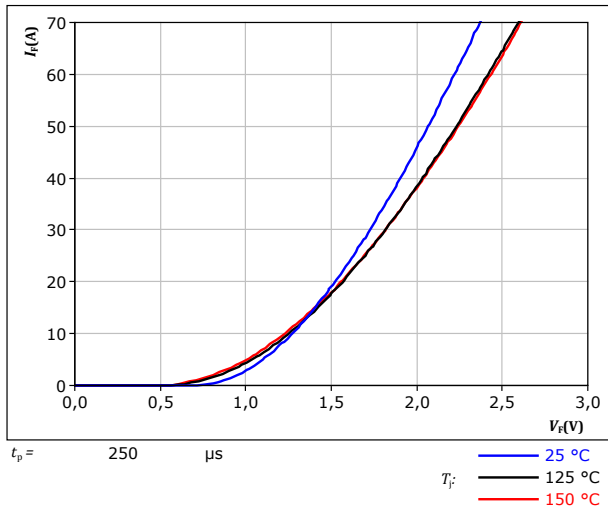
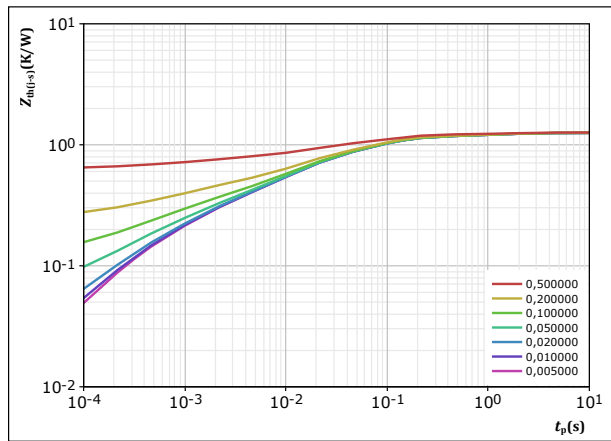


figure 8. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,263 \text{ K/W}$
 FWD thermal model values

| R (K/W) | τ (s) |
|-----------|------------|
| 2,32E-02 | 6,90E+01 |
| 1,03E-01 | 1,11E+00 |
| 4,95E-01 | 7,46E-02 |
| 4,02E-01 | 1,19E-02 |
| 1,68E-01 | 1,23E-03 |
| 8,19E-02 | 2,34E-04 |

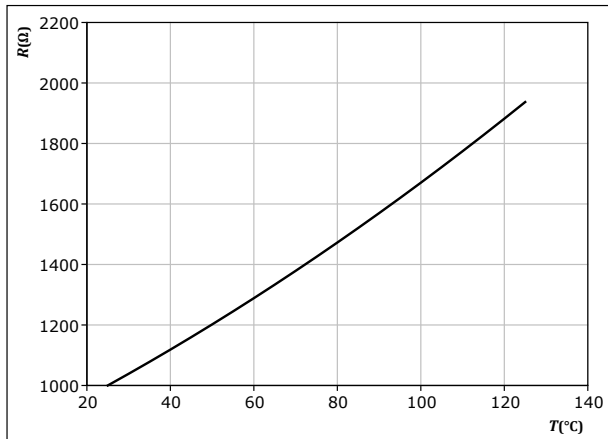


Thermistor Characteristics

figure 9. Thermistor

Typical PTC characteristic as function of temperature

$$R_T = f(T)$$

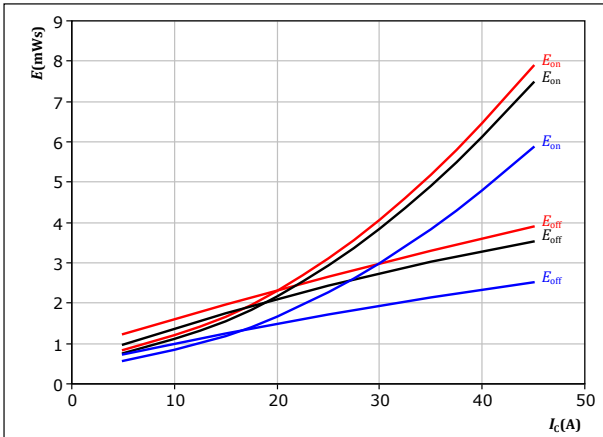




Inverter Switching Characteristics

figure 10. IGBT

Typical switching energy losses as a function of collector current
 $E = f(I_c)$

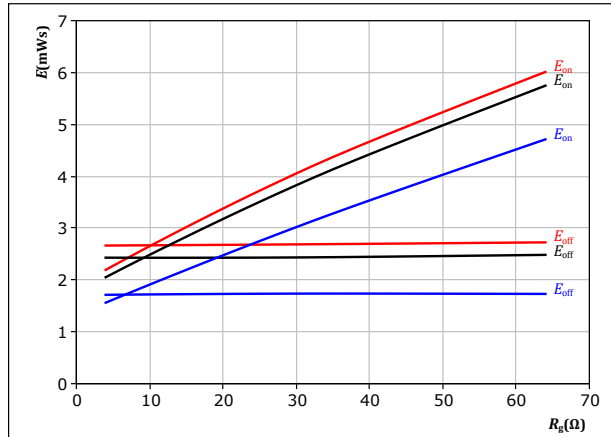


With an inductive load at

| | | | | |
|--------------|-----|---|--------|--------|
| $V_{CE} =$ | 600 | V | $T_j:$ | 25 °C |
| $V_{GE} =$ | ±15 | V | | 125 °C |
| $R_{gon} =$ | 16 | Ω | | 150 °C |
| $R_{goff} =$ | 16 | Ω | | |

figure 11. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$

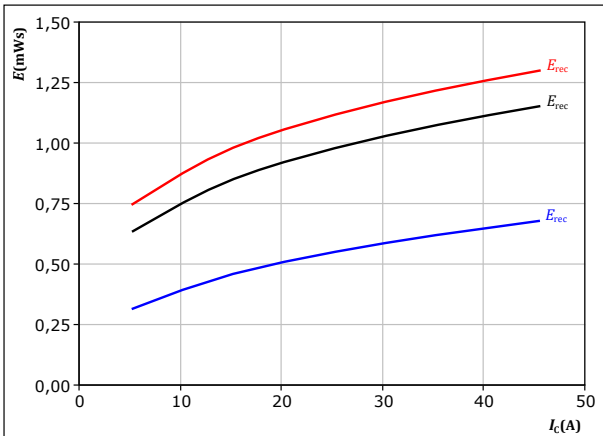


With an inductive load at

| | | | | |
|------------|-----|---|--------|--------|
| $V_{CE} =$ | 600 | V | $T_j:$ | 25 °C |
| $V_{GE} =$ | ±15 | V | | 125 °C |
| $I_c =$ | 25 | A | | 150 °C |

figure 12. FWD

Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$

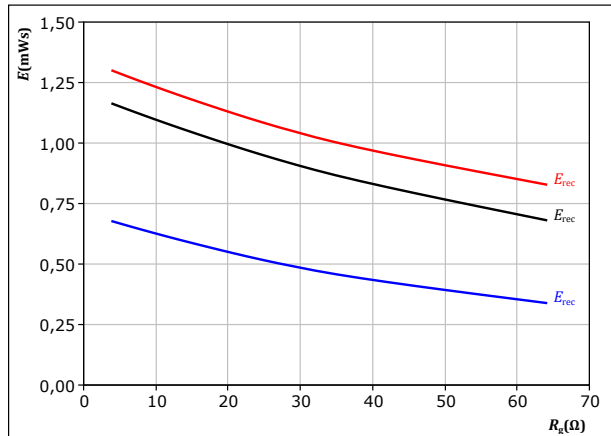


With an inductive load at

| | | | | |
|-------------|-----|---|--------|--------|
| $V_{CE} =$ | 600 | V | $T_j:$ | 25 °C |
| $V_{GE} =$ | ±15 | V | | 125 °C |
| $R_{gon} =$ | 16 | Ω | | 150 °C |

figure 13. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at

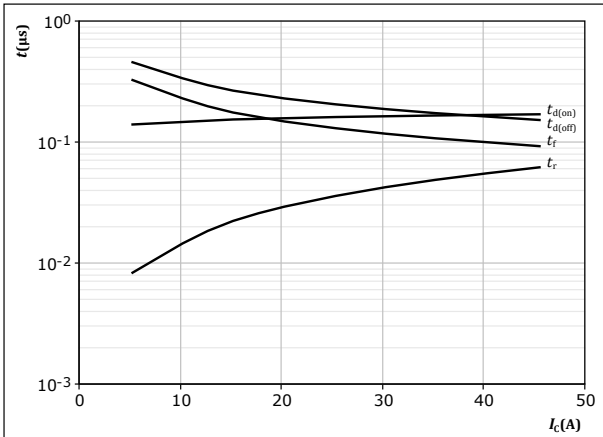
| | | | | |
|------------|-----|---|--------|--------|
| $V_{CE} =$ | 600 | V | $T_j:$ | 25 °C |
| $V_{GE} =$ | ±15 | V | | 125 °C |
| $I_c =$ | 25 | A | | 150 °C |



Inverter Switching Characteristics

figure 14. IGBT

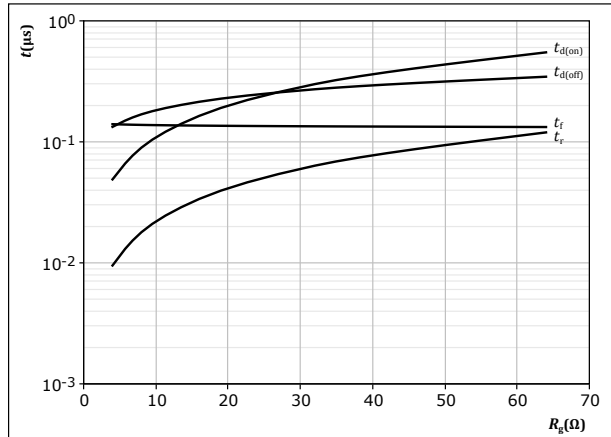
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $R_{goff} = 16 \text{ } \Omega$

figure 15. IGBT

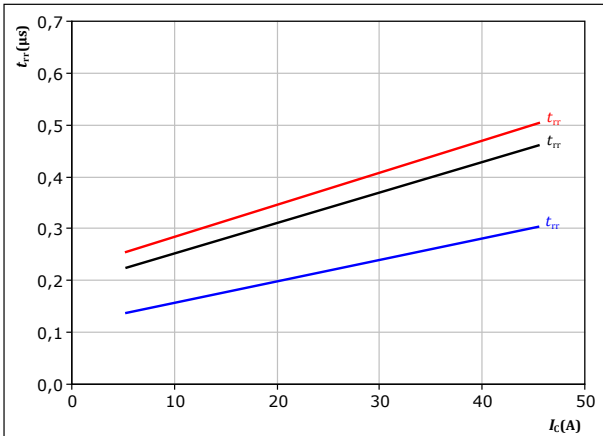
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 25 \text{ A}$

figure 16. FWD

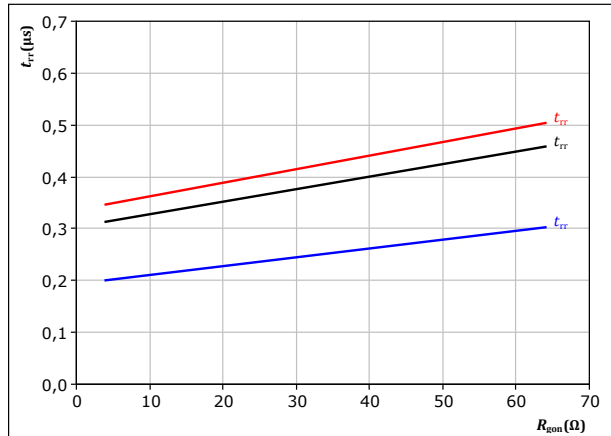
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 17. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 25 \text{ A}$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

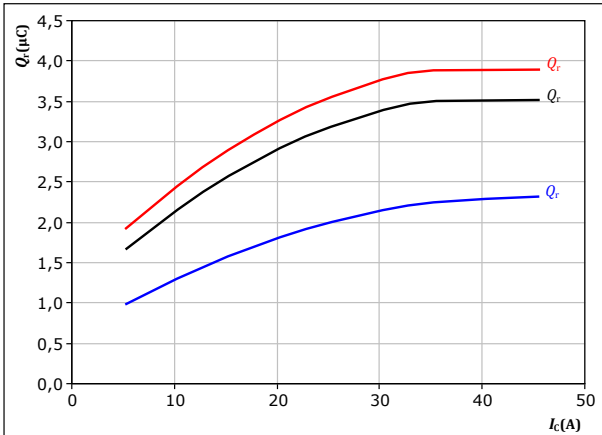


Inverter Switching Characteristics

figure 18. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

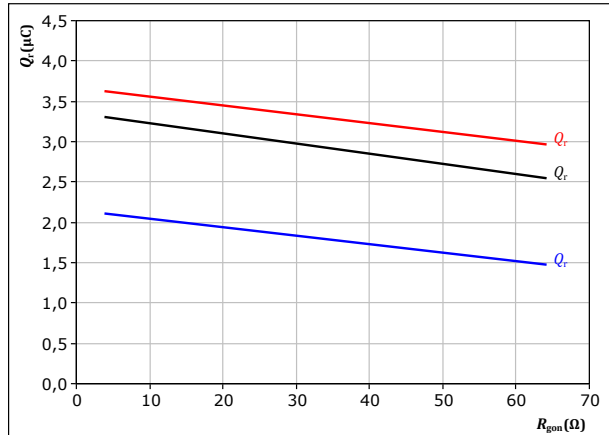
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 19. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

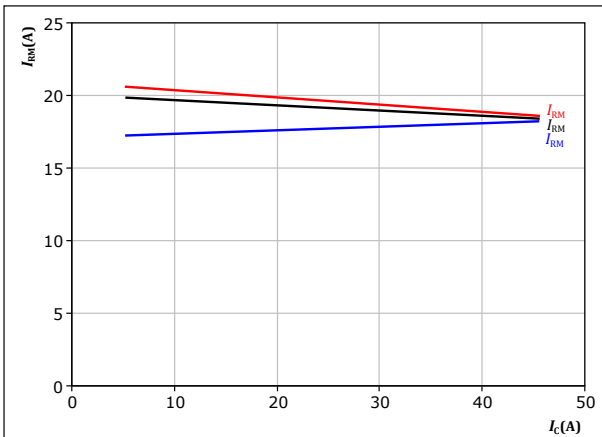
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 25$ A

T_j : — 25 °C
— 125 °C
— 150 °C

figure 20. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

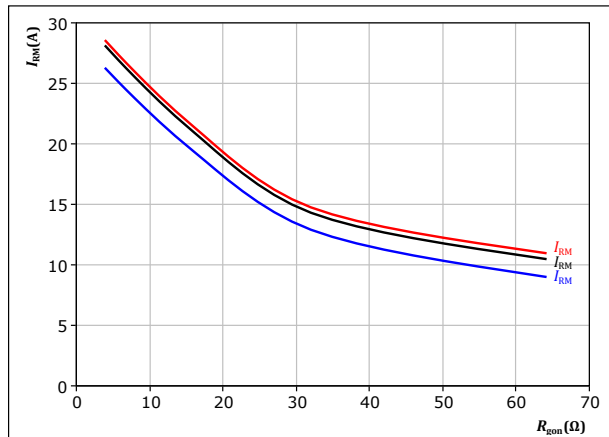
$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 21. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 25$ A

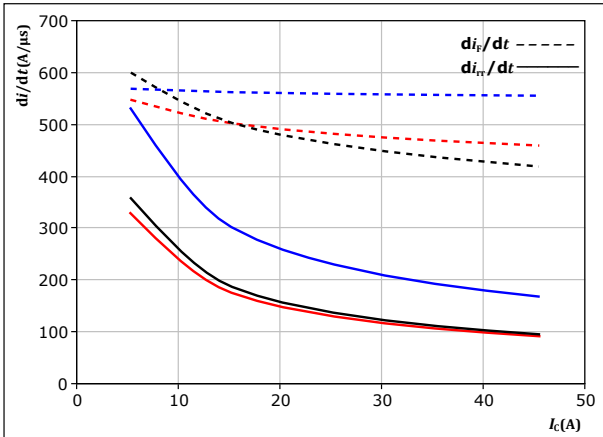
T_j : — 25 °C
— 125 °C
— 150 °C



Inverter Switching Characteristics

figure 22. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_c)$

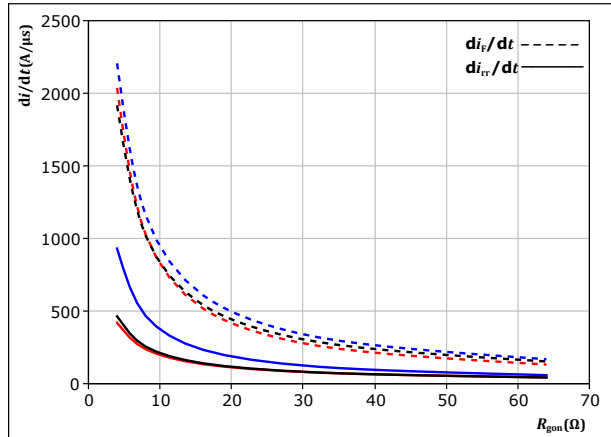


With an inductive load at

| | | | |
|-------------|-------|---------|--------|
| $V_{CE} =$ | 600 V | $T_j =$ | 25 °C |
| $V_{GE} =$ | ±15 V | | 125 °C |
| $R_{gon} =$ | 16 Ω | | 150 °C |

figure 23. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$

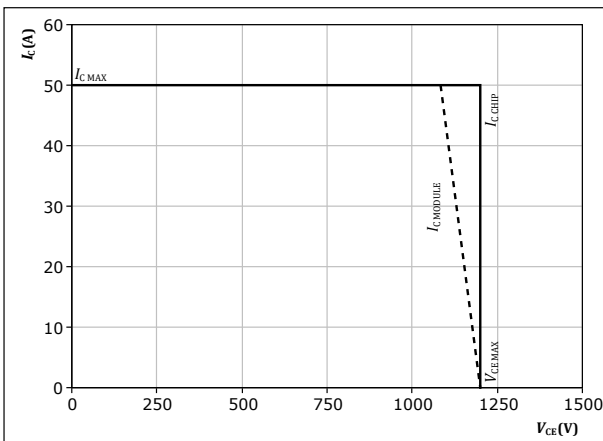


With an inductive load at

| | | | |
|------------|-------|---------|--------|
| $V_{CE} =$ | 600 V | $T_j =$ | 25 °C |
| $V_{GE} =$ | ±15 V | | 125 °C |
| $I_c =$ | 25 A | | 150 °C |

figure 24. IGBT

Reverse bias safe operating area
 $I_c = f(V_{CE})$



At $T_j = 150$ °C
 $R_{gon} = 16$ Ω
 $R_{goff} = 16$ Ω



Inverter Switching Definitions

figure 25. IGBT
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

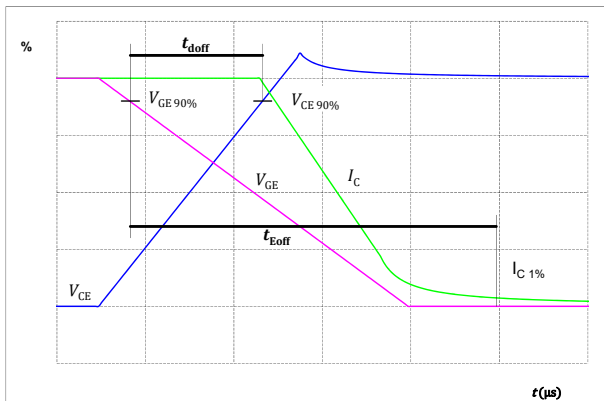


figure 26. IGBT
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

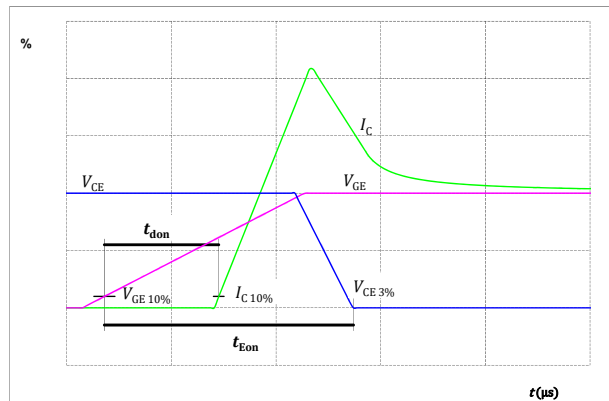


figure 27. IGBT
Turn-off Switching Waveforms & definition of t_f

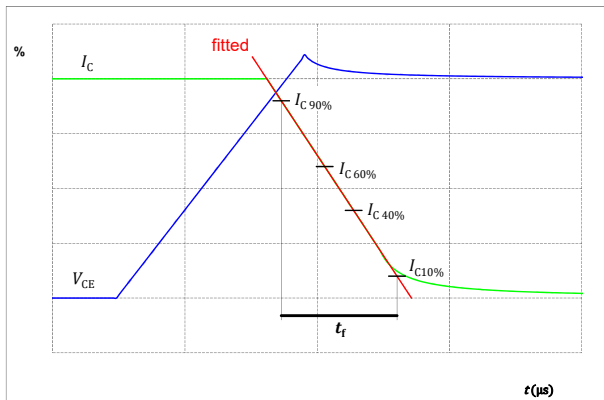
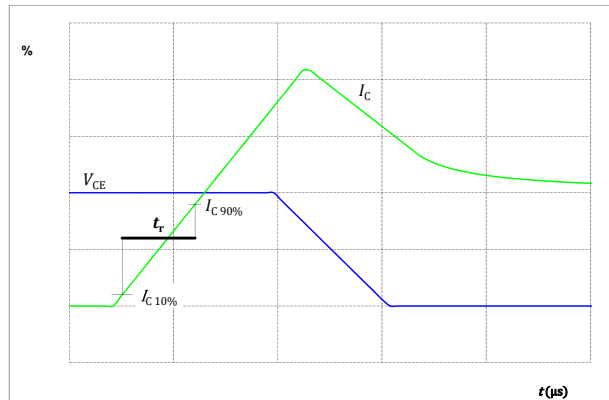


figure 28. IGBT
Turn-on Switching Waveforms & definition of t_r





Inverter Switching Definitions

figure 29. FWD

Turn-off Switching Waveforms & definition of t_{rr}

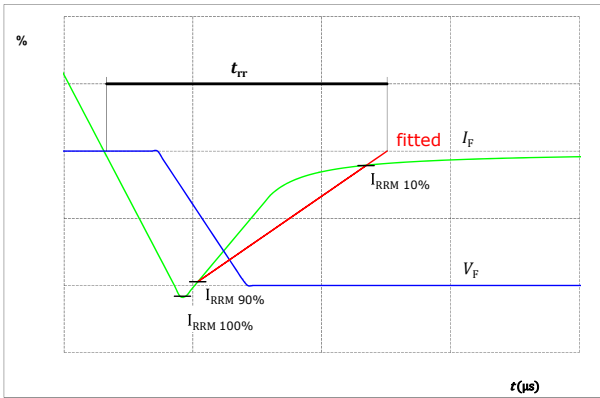
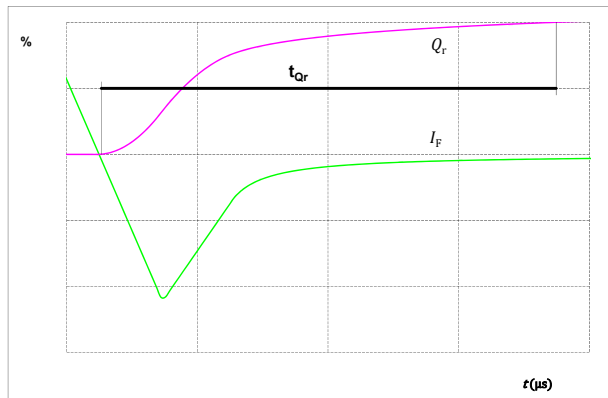


figure 30. FWD


Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



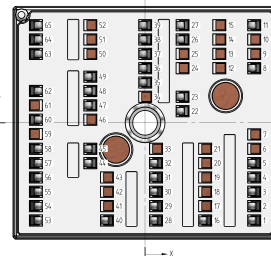


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| Ordering Code | |
|--|------------------------------|
| Version | Ordering Code |
| With std lid (6.5mm height) + no thermal grease | 80-M2126PA025M7-K716F70-/0A/ |
| With thin lid (2.8mm height) + no thermal grease | 80-M2126PA025M7-K716F70-/0B/ |
| With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based) | 80-M2126PA025M7-K716F70-/1A/ |
| With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based) | 80-M2126PA025M7-K716F70-/1B/ |
| With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free) | 80-M2126PA025M7-K716F70-/4A/ |
| With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free) | 80-M2126PA025M7-K716F70-/4B/ |
| With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based) | 80-M2126PA025M7-K716F70-/5A/ |
| With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based) | 80-M2126PA025M7-K716F70-/5B/ |

| Marking | | | | | | |
|------------|---|--------------------------------|------------|----------|-----------|--------|
| Text | Name | | Date code | UL & VIN | Lot | Serial |
| |  | NN-NNNNNNNNNNNNNN- TTTTTTVV | | WWYY | UL VIN | LLLLL |
| Datamatrix | | Type&Ver | Lot number | Serial | Date code | |
| | TTTTTTVV | LLLLL | SSSS | WWYY | | |

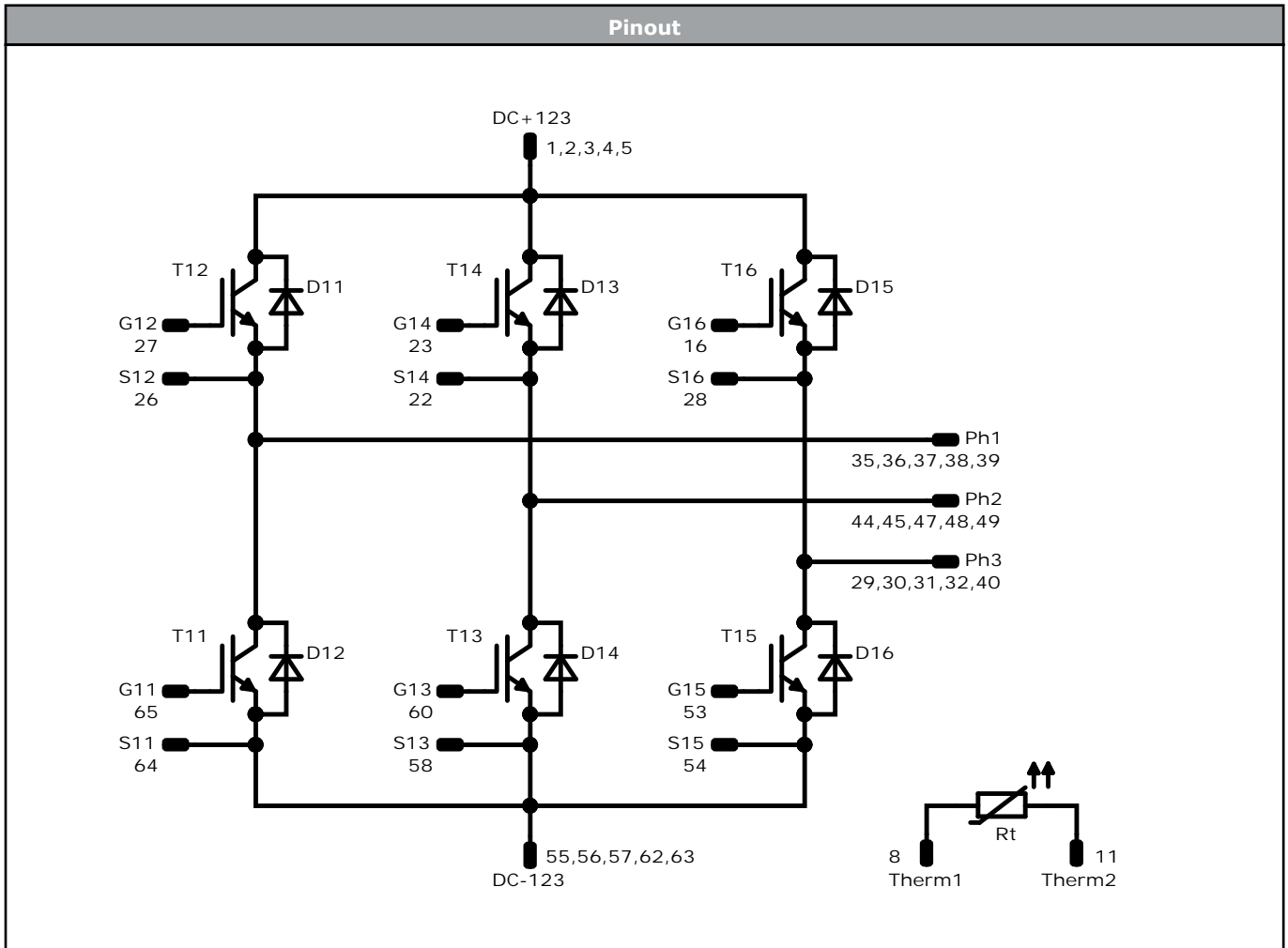
| Outline | | | | | | | |
|----------------|---------------|-------|----------|----|---------------|-------|--------|
| Pin table [mm] | | | | | | | |
| Pin | X | Y | Function | 34 | not assembled | | |
| 1 | 24,38 | -21,8 | DC+123 | 35 | 0,03 | 9 | Ph1 |
| 2 | 24,38 | -18,6 | DC+123 | 36 | 0,03 | 12,2 | Ph1 |
| 3 | 24,38 | -15,4 | DC+123 | 37 | 0,03 | 15,4 | Ph1 |
| 4 | 24,38 | -12,2 | DC+123 | 38 | 0,03 | 18,6 | Ph1 |
| 5 | 24,38 | -9 | DC+123 | 39 | 0,03 | 21,8 | Ph1 |
| 6 | not assembled | | | 40 | -8,5 | -21,8 | Ph3 |
| 7 | not assembled | | | 41 | not assembled | | |
| 8 | 24,38 | 12,2 | Therm1 | 42 | not assembled | | |
| 9 | not assembled | | | 43 | not assembled | | |
| 10 | not assembled | | | 44 | -12,22 | -9 | Ph2 |
| 11 | 24,38 | 21,8 | Therm2 | 45 | -12,22 | -5,8 | Ph2 |
| 12 | not assembled | | | 46 | not assembled | | |
| 13 | not assembled | | | 47 | -12,22 | 3,9 | Ph2 |
| 14 | not assembled | | | 48 | -12,22 | 7,1 | Ph2 |
| 15 | not assembled | | | 49 | -12,22 | 10,3 | Ph2 |
| 16 | 13,42 | -21,8 | G16 | 50 | not assembled | | |
| 17 | not assembled | | | 51 | not assembled | | |
| 18 | not assembled | | | 52 | not assembled | | |
| 19 | not assembled | | | 53 | -24,38 | -21,8 | G15 |
| 20 | not assembled | | | 54 | -24,38 | -18,6 | S15 |
| 21 | not assembled | | | 55 | -24,38 | -15,4 | DC-123 |
| 22 | 8,38 | 2,6 | S14 | 56 | -24,38 | -12,2 | DC-123 |
| 23 | 8,38 | 5,8 | G14 | 57 | -24,38 | -9 | DC-123 |
| 24 | not assembled | | | 58 | -24,38 | -5,8 | S13 |
| 25 | not assembled | | | 59 | not assembled | | |
| 26 | 8,38 | 18,6 | S12 | 60 | -24,38 | 0,7 | G13 |
| 27 | 8,38 | 21,8 | G12 | 61 | not assembled | | |
| 28 | 2,46 | -21,8 | S16 | 62 | -24,38 | 7,1 | DC-123 |
| 29 | 2,46 | -18,6 | Ph3 | 63 | -24,38 | 15,4 | DC-123 |
| 30 | 2,46 | -15,4 | Ph3 | 64 | -24,38 | 18,6 | S11 |
| 31 | 2,46 | -12,2 | Ph3 | 65 | -24,38 | 21,8 | G11 |
| 32 | 2,46 | -9 | Ph3 | | | | |
| 33 | not assembled | | | | | | |



Pad positions refers to center point. For more informations on pad design please see package data



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| Identification | | | | | |
|------------------------------|-----------|---------|---------|-----------------|---------|
| ID | Component | Voltage | Current | Function | Comment |
| T11, T12, T13, T14, T15, T16 | IGBT | 1200 V | 25 A | Inverter Switch | |
| D11, D12, D13, D14, D15, D16 | FWD | 1200 V | 25 A | Inverter Diode | |
| Rt | PTC | | | Thermistor | |



| Packaging instruction | | | | |
|--------------------------------------|------|----------|------|--------|
| Standard packaging quantity (SPQ) 72 | >SPQ | Standard | <SPQ | Sample |

| Handling instruction |
|--|
| Handling instructions for MiniSKiiP® 2 packages see vincotech.com website. |

| Package data |
|---|
| Package data for MiniSKiiP® 2 packages see vincotech.com website. |

| Vincotech thermistor reference |
|--|
| See Vincotech thermistor reference table at vincotech.com website. |

| UL recognition and file number |
|--|
| This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=150^{\circ}C$ and up to 2500VAC/1min isolation voltage. For more information see vincotech.com website. |



| Document No.: | Date: | Modification: | Pages |
|-------------------------------|--------------|-----------------|-------|
| 80-M2126PA025M7-K716F70-D1-14 | 18 Nov. 2024 | Initial Release | |

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.